



ORIENTAL
SEMICONDUCTOR

OSG65R900xTF_Datasheet

GreenMOS™

Green
PRODUCT

RoHS
compliant

Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

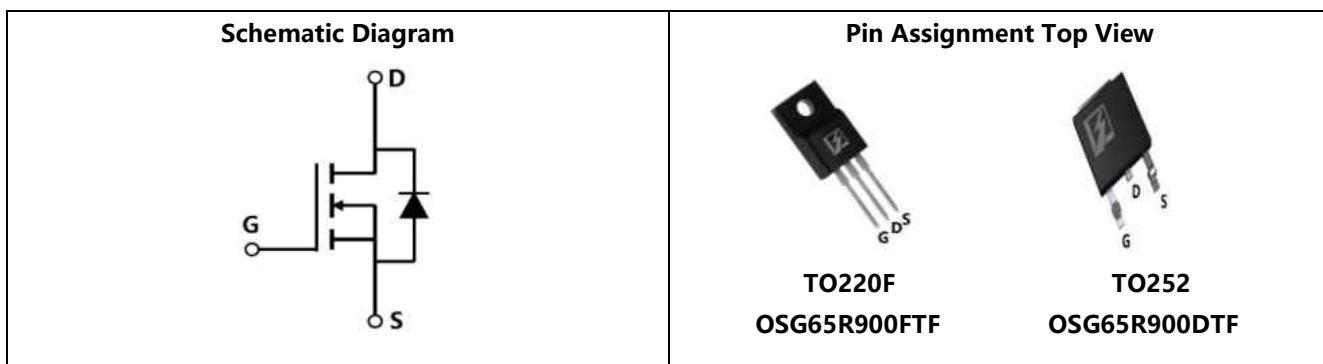
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

■ General Description

OSG65R900xTF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ $V_{DS, min@Tjmax}$	700 V
◆ $I_D, pulse$	13.5 A
◆ $R_{DS(ON)}, \text{max } @ VGS=10 \text{ V}$	900 mΩ
◆ Q_g	7.1 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	650	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	4.5	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		2.8	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	13.5	A
Power dissipation ³⁾ for TO252, $T_C=25^\circ\text{C}$	P_D	32	W
Power dissipation ³⁾ for TO220F, $T_C=25^\circ\text{C}$		25	
Single pulsed avalanche energy ⁵⁾	E_{AS}	50	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...480 \text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...480 \text{ V}, I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO252	TO220F	
Thermal resistance, junction-case	R _{θJC}	3.9	5.0	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	650			V	V _{GS} =0 V, I _D =250 μA
		700				V _{GS} =0 V, I _D =250 μA T _j =150 °C
Gate threshold voltage	V _{GS(th)}	2.9		3.9	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}		0.75	0.9	Ω	V _{GS} =10 V, I _D =2 A
			1.75			V _{GS} =10 V, I _D =2 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =650 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		324.1		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		30.1		pF	
Reverse transfer capacitance	C _{rss}		1.6		pF	
Turn-on delay time	t _{d(on)}		22.8		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =2 A
Rise time	t _r		11.5		ns	
Turn-off delay time	t _{d(off)}		48.7		ns	
Fall time	t _f		14.9		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		7.1		nC	$I_D=2\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		1.5		nC	
Gate-drain charge	Q_{gd}		3.5		nC	
Gate plateau voltage	$V_{plateau}$		5.8		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			4.5	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			13.5		
Diode forward voltage	V_{SD}			1.3	V	$I_S=4.5\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		147.0		ns	$V_R=400\text{ V}$, $I_S=2\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		0.92		μC	
Peak reverse recovery current	I_{rrm}		12.4		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=50\text{ }\Omega$, $L=60\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

■ Electrical Characteristics Diagrams

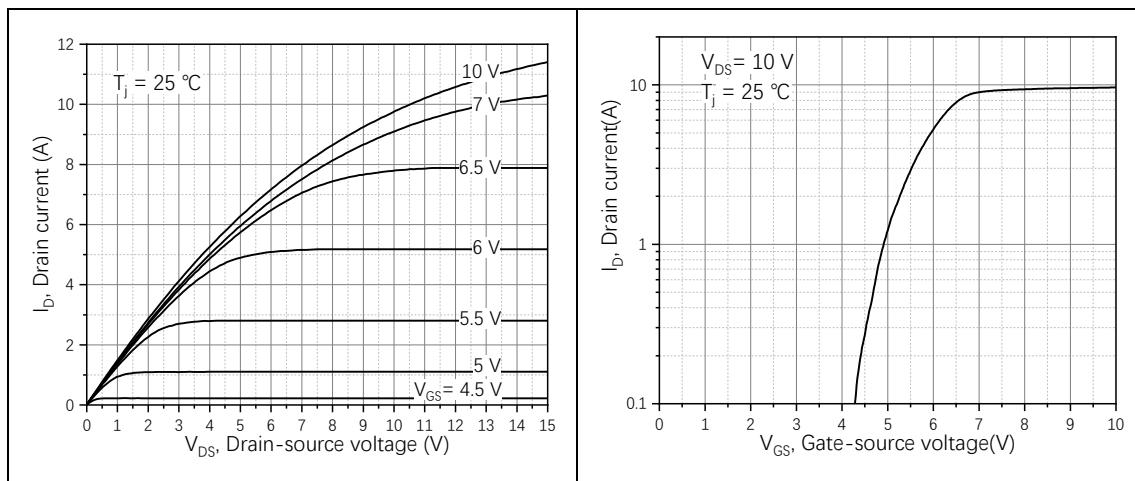


Figure 1, Typ. output characteristics

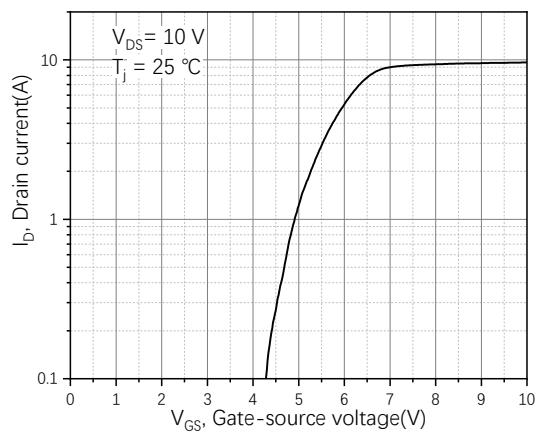


Figure 2, Typ. transfer characteristics

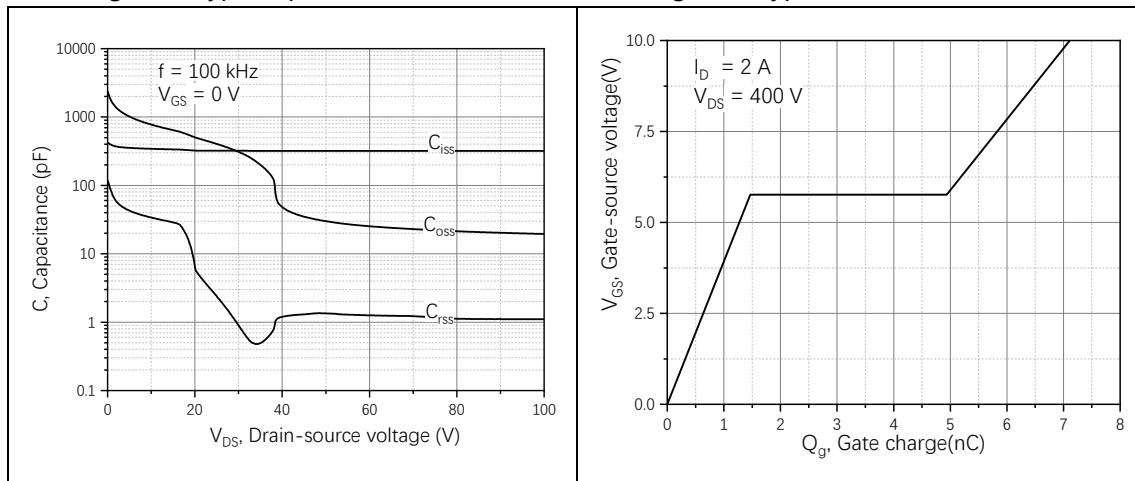


Figure 3, Typ. capacitances

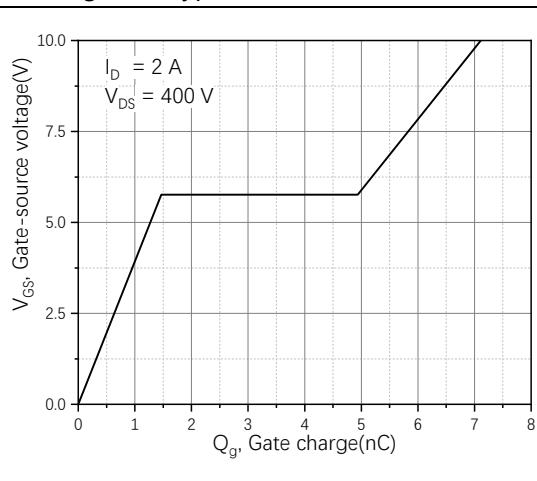


Figure 4, Typ. gate charge

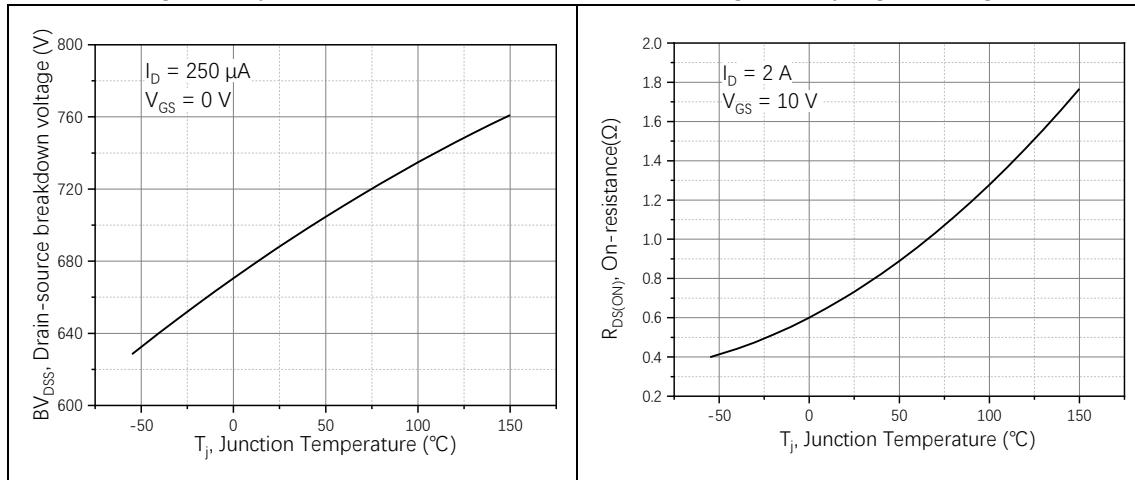


Figure 5, Drain-source breakdown voltage

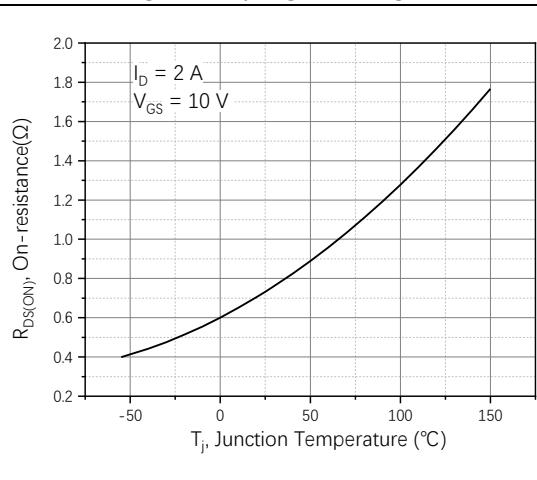


Figure 6, Drain-source on-state resistance

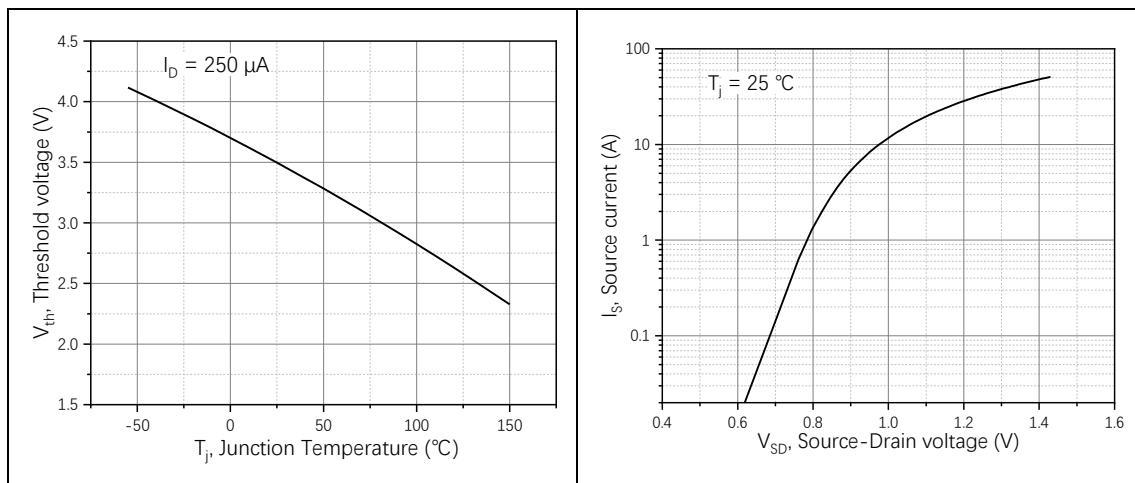


Figure 7, Threshold voltage

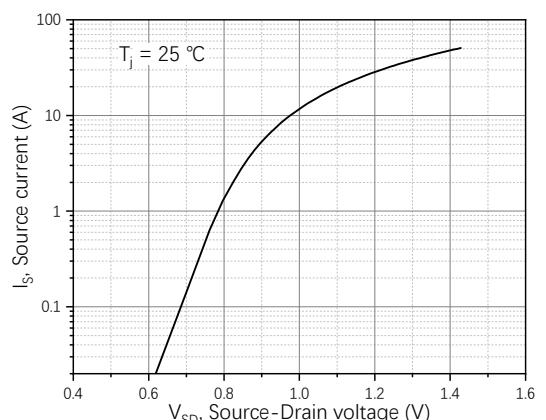


Figure 8, Forward characteristic of body diode

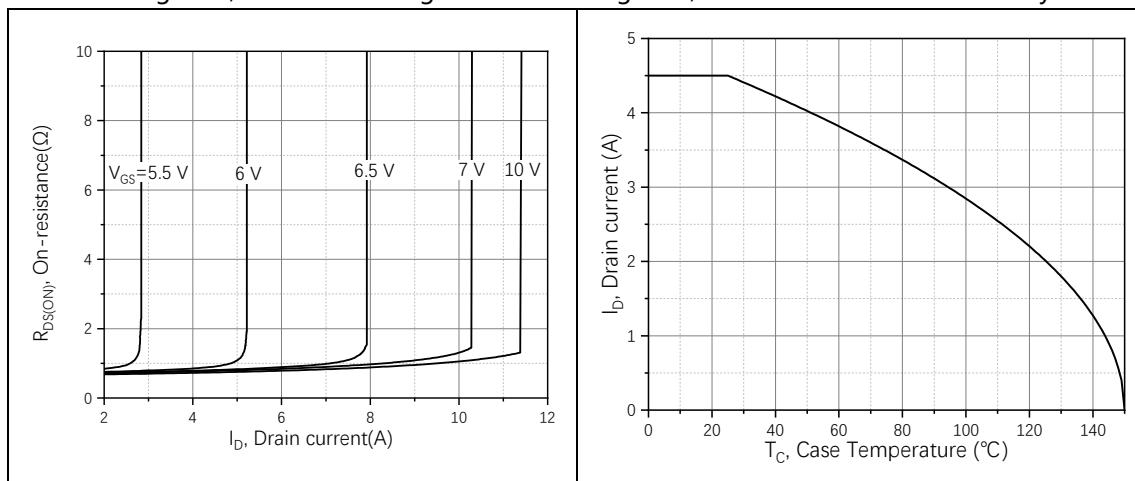


Figure 9, Drain-source on-state resistance

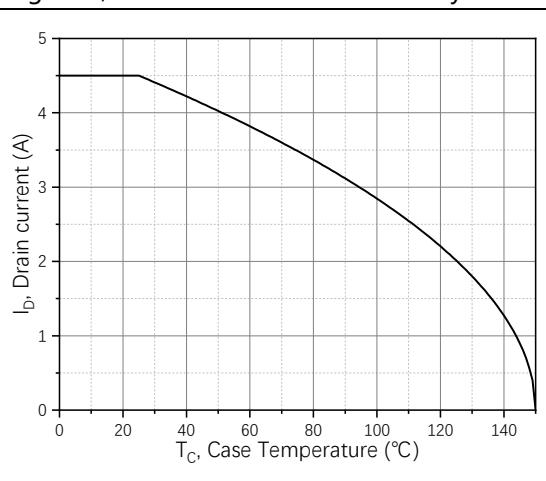


Figure 10, Drain current

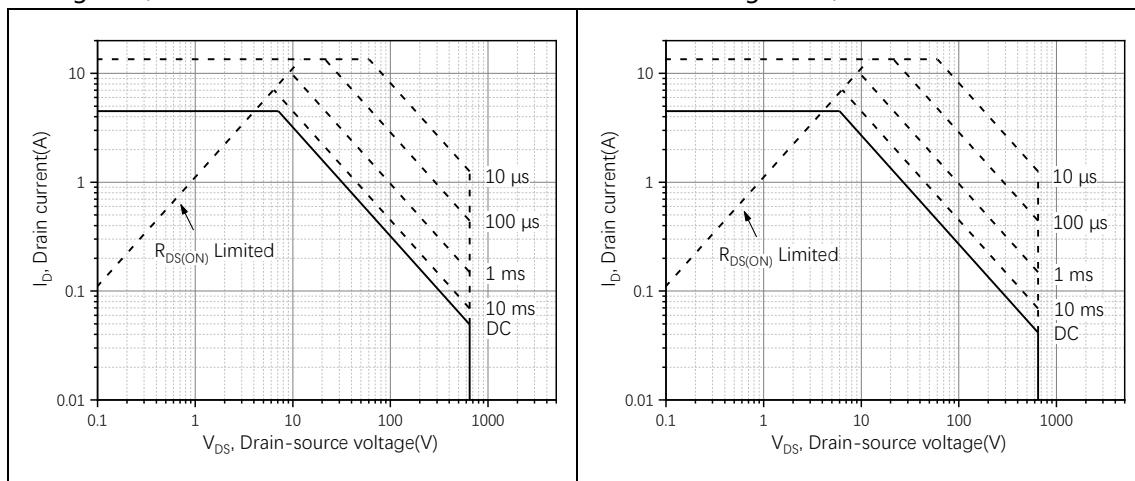


Figure 11, Safe operation area for TO252

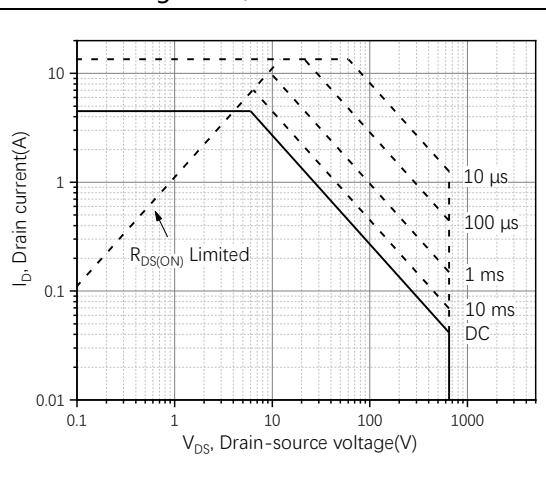
 $T_C = 25 \text{ } ^\circ\text{C}$


Figure 12, Safe operation area for TO220F

 $T_C = 25 \text{ } ^\circ\text{C}$

■ Test circuits and waveforms

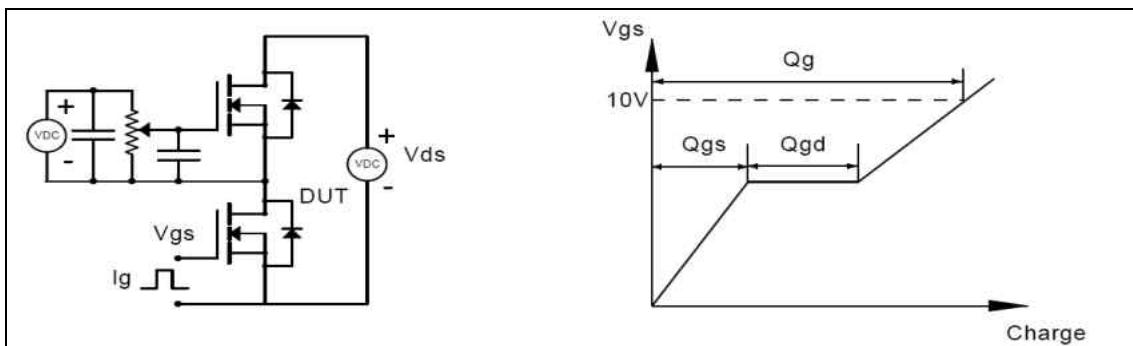


Figure 1, Gate charge test circuit & waveform

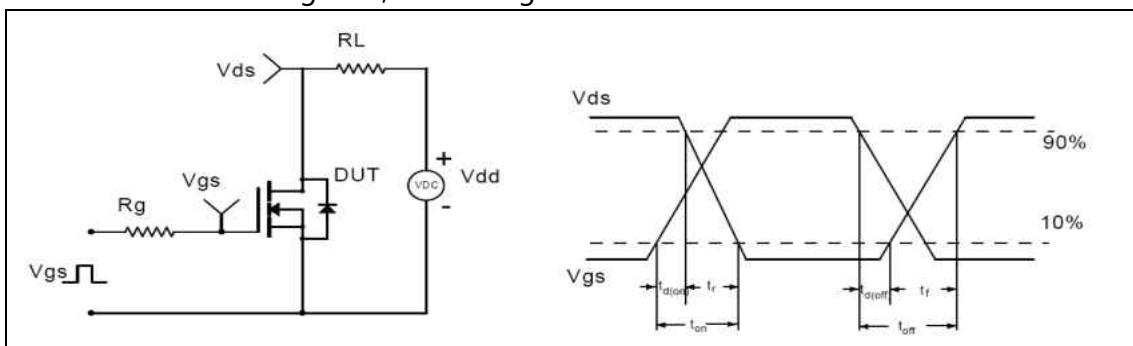


Figure 2, Switching time test circuit & waveforms

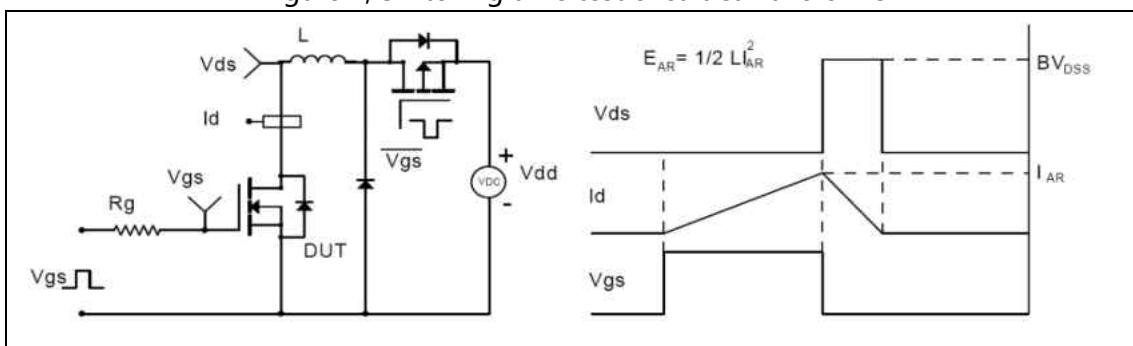


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

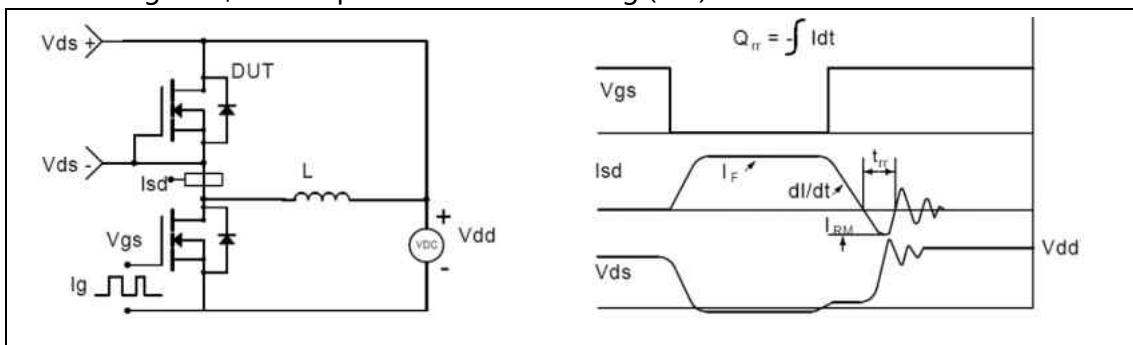
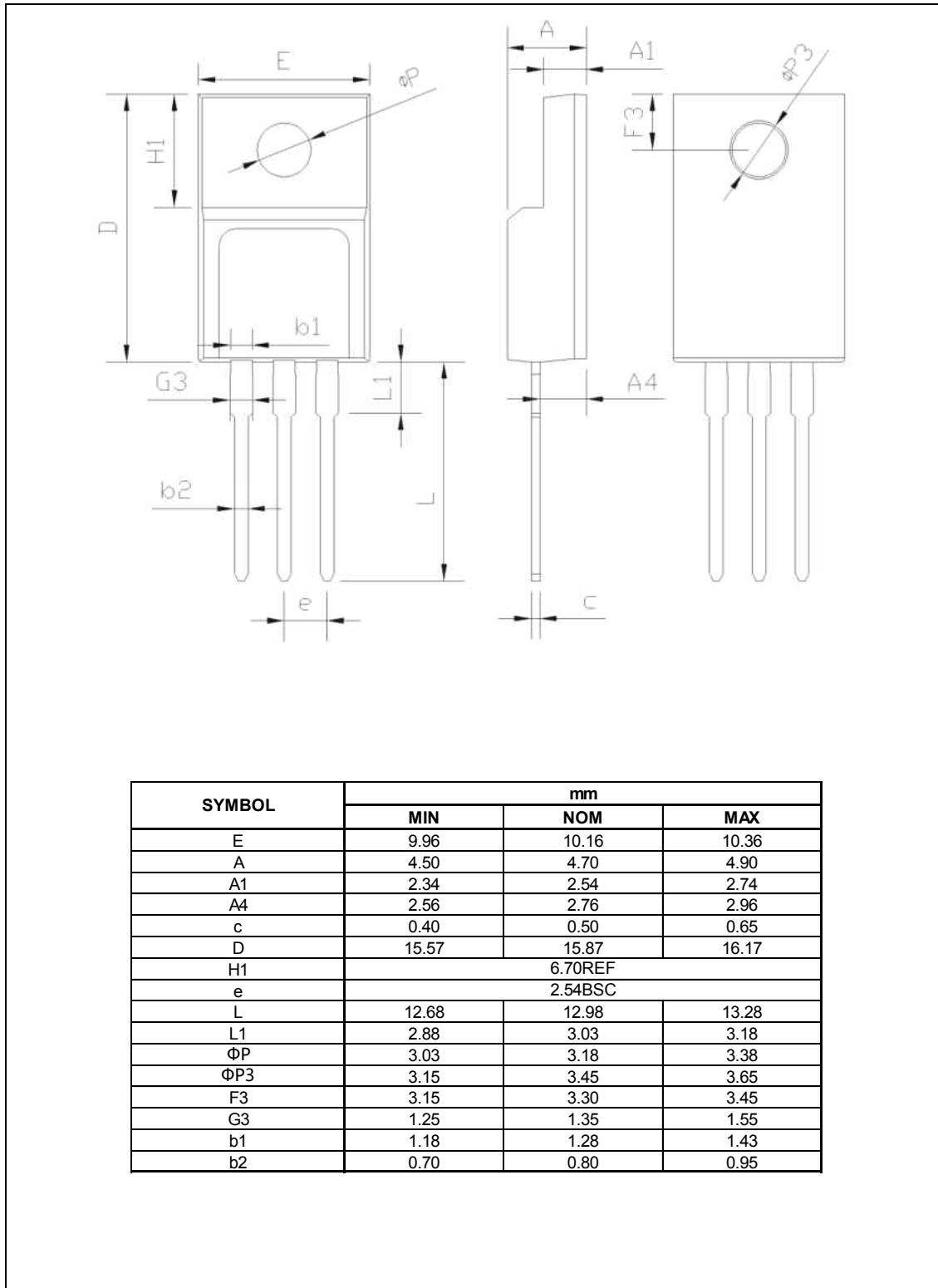


Figure 4, Diode reverse recovery test circuit & waveforms

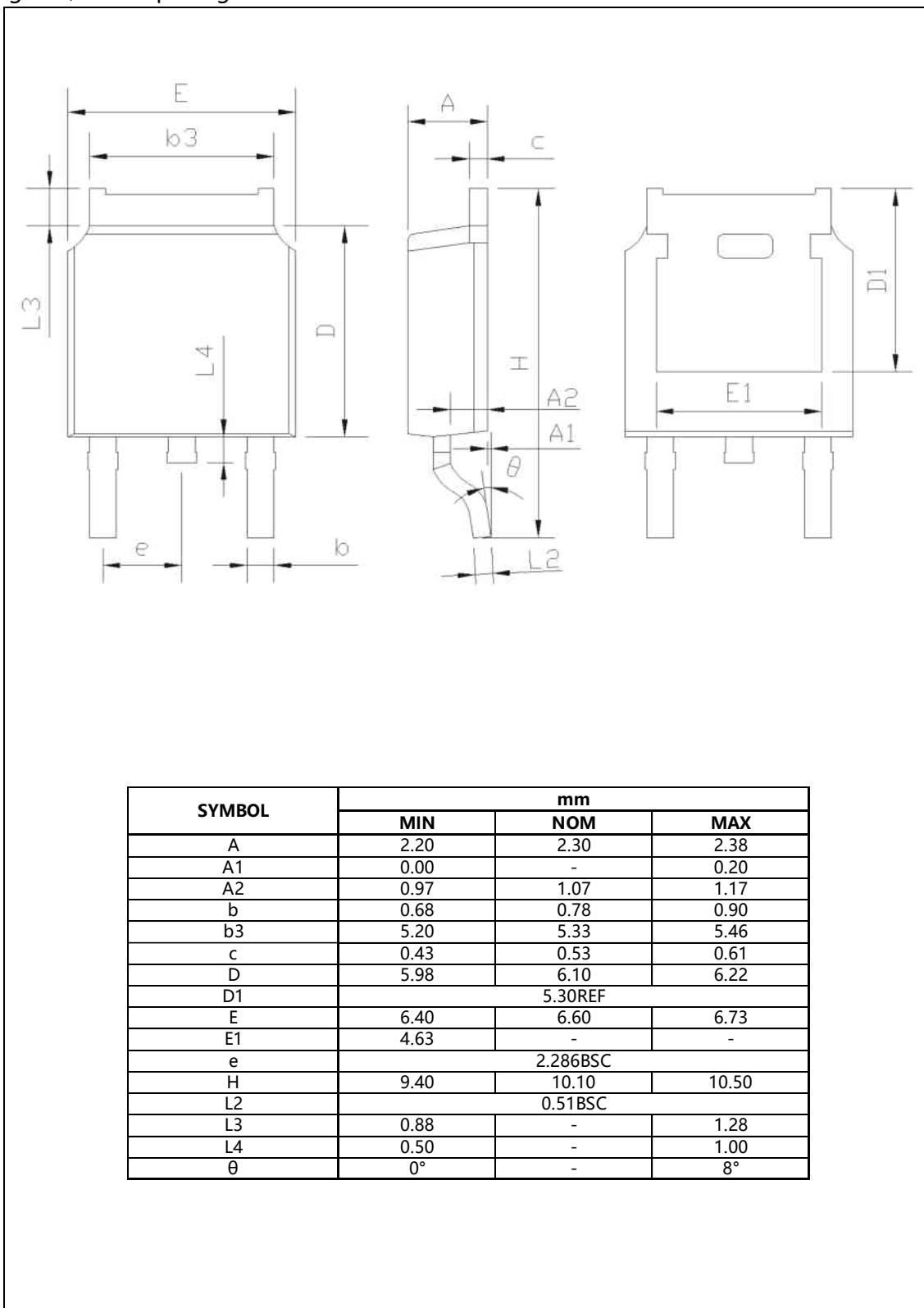
■ Package Information

Figure1, TO220F package outline dimension



■ Package Information

Figure2, TO252 package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO220F	50	20	1000	6	6000

Package	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO252	2500	2	5000	5	25000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R900FTF	TO220F	yes	yes	yes
OSG65R900DTF	TO252	yes	yes	yes